High Capacitance Series



1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC high capacitance MLCC offers low ESR and excellent frequency characteristics to be suited for coupling and decoupling applications in circuit. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

2. FEATURES

- a. Small size with high capacitance.
- b. Capacitor with lead-free termination (pure Tin).

3. APPLICATIONS

- Digital circuit coupling or decoupling applications.
- b. For high frequency and high-density type power suppliers.
- c. For bypassing.

4. HOW TO ORDER

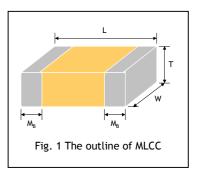
<u>1206</u>	<u>F</u>	<u>106</u>	<u>Z</u>	<u>100</u>	<u>C</u>	Ī
<u>Size</u>	Dielectric	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	<u>Packaging</u>
Inch (mm)	B =X7R X =X5R	Tivo cianificant digita	K=±10%	Two significant digits	C C. /Ni /Sa	T=7" reeled
Inch (mm)		Two significant digits		Two significant digits	C=Cu/NI/SII	
0402 (1005)	F=Y5V	followed by no. of	M=±20%	followed by no. of		G=13" reeled
0603 (1608)		zeros. And R is in place	Z =-20/+80%	zeros. And R is in		
0805 (2012)		of decimal point.		place of decimal		
1206 (3216)				point.		
1210 (3225)		eg.:				
1812 (4532)		106=10x10 ⁶		6R3 =6.3 VDC		
		=10µF		100 =10 VDC		
				160 =16 VDC		
				250 =25 VDC		
				500 =50 VDC		

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5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbo	l	Remark	M _B (mm)
0402 (1005)	1.00±0.05	0.50±0.05	0.50±0.05	N		0.25 +0.05/-0.10
0603 (1608)	1.60±0.10	0.80±0.10	0.80±0.07	S		0.40±0.15
0003 (1006)	1.60+0.15/-0.10	0.80+0.15/-0.10	0.80+0.15/-0.10	Х		0.40±0.15
	2.00±0.15	1.25+0.10	0.80±0.10	В		
0805 (2012)	2.00±0.13	1.23±0.10	1.25±0.10	D	#	0.50±0.20
	2.00±0.20	1.25±0.20	1.25±0.20	ı	#	
		1.60±0.15	0.95±0.10	С	#	
	3.20±0.15	1.00±0.13	1.25±0.10	D	#	
1206 (3216)		1.60±0.20	1.60±0.20	G	#	0.60±0.20
	3.20±0.20	1.00±0.20	1.15±0.15	J	#	
	3.20+0.30/-0.10	1.60+0.30/-0.10	1.60+0.30/-0.10	Р	#	
	3.20+0.30	2.50±0.20	0.95±0.10	С	#	
	3.20±0.30	2.30±0.20	1.25±0.10	D	#	
1210 (3225)			1.60±0.20	G	#	0.75±0.25
	3.20±0.40	2.50±0.30	2.00±0.20	K	#	
			2.50±0.30	M	#	
			1.25±0.10	D	#	
1812 (4532)	4.50±0.40	3.20±0.30	2.00±0.20	K	#	0.75±0.25
			2.50±0.30	M	#	



6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X5R	Y5V						
Size	0402, 0603, 0805, 1206, 1210, 1812								
Capacitance range*	100nF to 4.7μF 100nF to 10μF 150nF to								
Capacitance tolerance	K (±10%), M (±20%) M (±20%), Z (-20/								
Rated voltage (WVDC)	6.3V, 10V, 16V, 25V, 50V								
Tan δ^*		Note 1							
Insulation resistance at Ur		RxC≥500ΩxF							
Operating temperature	-55 to +125°C	-55 to +85°C	-25 to +85°C						
Capacitance characteristic	±15% +30/-80%								
Termination		Ni/Sn (lead-free termination)							

^{*} Measured at 1.0 \pm 0.2Vrms, 1.0kHz \pm 10% for C \leq 10 μ F; 0.5 \pm 0.2Vrms, 120Hz \pm 20% for C>10 μ F, 30~70% related humidity, 25°C ambient temperature for X7R, X5R and at 20°C for Y5V.

X7R/X5R

Rated vol.	D.F.	Except	Exception of D.F.						
≥50V	≤2.5%	≤3%	0603≥0.047μF; 0805≥0.18μF, 1206≥0.47μF						
25V	≤3.5%	≤5%	0805≥1μF						
16V	≤3.5%	< 5%	0402≥0.033μF; 0603≥0.15μF; 0805≥0.68μF; 1206≥2.2μF						
10V	≤5.0%								
6.3V	≤7.5%								

Y5V

Rated vol.	D.F.	Exception of D.F.						
≥50V	≤5.0%							
25V	≤5.0%	< 1%	0603≥0.1μF; 0805≥0.33μF; 1206≥1μF					
16V (C<1.0μF)	≤7.0%	≤ 9 %	0402≥0.068μF					
16V (C≥1.0μF)	≤9.0%							
≤10V	≤12.5%							

[#] Reflow soldering only is recommended.

^{*} Note 1

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7. CAPACITANCE RANGE

7-1 X7R Dielectric

	Dielectric										X7	'R									
	Size	0402	0603				0805		1206			1210				1812					
Rate	ed Voltage (VDC)	10	10	16	25	50	10	16	25	10	16	25	50	10	16	25	50	10	16	25	50
	0.10μF (104)	N	S	S	S	Х															
	0.15μF (154)		S	S																	
	0.22μF (224)		S	S																	
a)	0.33µF (334)		Χ	Х																	
ance	0.47μF (474)		Χ	Х																	
citi	0.68µF (684)																				
Capacitance	1.0µF (105)		Х				D	D	ı		D	D	Р			D	G			D	K
	1.5µF (155)																				
	2.2µF (225)									D	Р	Р		K	K	G					
	3.3µF (335)									Р											
	4.7μF (475)									Р											

^{1.} The letter in cell is expressed the symbol of product thickness.

7-2 X5R Dielectric

	Dielectric					X5R				
	Size		0402			0603		0805	12	.06
Rat	ed Voltage (VDC)	6.3	10	16	6.3	10	16	6.3	6.3	10
	0.027μF (273)			N						
	0.033µF (333)			N						
	0.039µF (393)			N						
	0.047µF (473)			N						
	0.056µF (563)		N							
	0.068µF (683)		N							
	0.082µF (823)		N							
	0.10µF (104)		N							
9	0.15µF (154)									
itan	0.22µF (224)									
Capacitance	0.33µF (334)					Х	Х			
g	0.47µF (474)					Х	Х			
	0.68µF (684)				Х					
	1.0µF (105)				Х					
	1.5µF (155)									
	2.2µF (225)							I		Р
	3.3µF (335)									Р
	4.7μF (475)									Р
	6.8µF (685)								Р	Р
	10μF (106)								Р	Р

^{1.} The letter in cell is expressed the symbol of product thickness.

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7-3 Y5V Dielectric

	Dielectric									Y!	5V								
	Size		0402 0603			0805		1206			1210			1812					
Ra	ted Voltage (VDC)	6.3	10	10	16	10	16	25	10	16	25	35	50	10	16	25	50	25	50
	0.15µF (154)		N																
	0.22µF (224)		N																
	0.33µF (334)	N																	
	0.47µF (474)	N																	
	0.68µF (684)	N																	
9	1.0µF (105)	N		S	Х	В	В	D		В	С		С				С		D
Capacitance	1.5µF (155)			S		D	D			С	С					С			D
pac	2.2µF (225)			S		D	D			С	С					С			D
Ca	3.3µF (335)					D	D		J	J	J					С			D
	4.7µF (475)					D	D		J	J	J				С	D			D
	6.8µF (685)					- 1			J	J					С	G			D
	10μF (106)					I			J	J		K			D	G		D	
	22μF (226)	•							Р					K					
	47μF (476)													K					

^{1.} The letter in cell is expressed the symbol of product thickness.

8. PACKAGING STYLE AND QUANTITY

C:	Thisler are (many) (Co	b.al	Pape	r tape	Plastic tape			
Size	Thickness (mm)/Sy	/mbol	7" reel	13" reel	7" reel	13" reel		
0402 (1005)	0.50±0.05	N	10k	50k	-	-		
0603 (1608)	0.80±0.07	S	4k	15k	-	-		
0003 (1006)	0.80+0.15/-0.10	X	4k	15k	-	-		
	0.80±0.10	В	4k	15k	-	-		
0805 (2012)	1.25±0.10	D	-	-	3k	10k		
	125±0.20	ı	-	-	3k	10k		
	0.95±0.10	С	-	-	3k	10k		
1206 (3216)	1.25±0.10	D	-	-	3k	10k		
1200 (3210)	1.60±0.20	G	-	-	2k	-		
	1.60+0.30/-0.10	Р	-	-	2k	-		
	0.95±0.10	С	-	-	3k	10k		
	1.25±0.10	D	-	-	3k	10k		
1210 (3225)	1.60±0.20	G	-	-	2k	-		
	2.00±0.20	K	-	-	1k	-		
	2.50±0.30	M	-	-	1k	-		
	1.25±0.10	D	-	-	1k	-		
1812 (4532)	2.00±0.20	K	-	-	1k	-		
	2.50±0.30	М	-	-	0.5k	-		

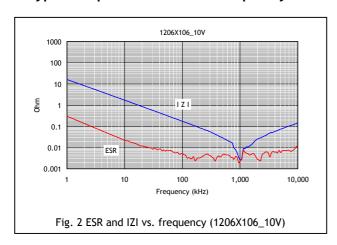
Unit: pieces

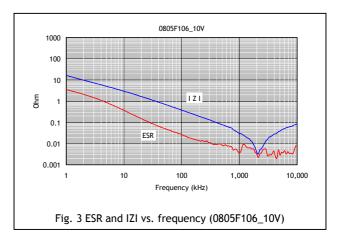
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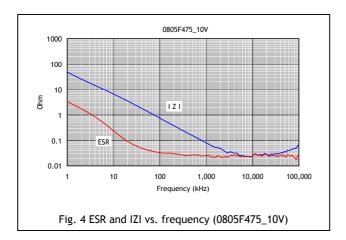


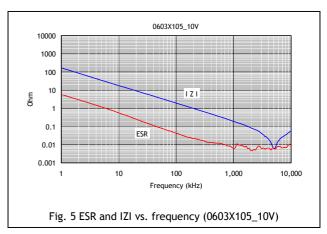
9. ELECTRICAL CHARACTERISTICS

■ Typical Impedance/ESR vs. Frequency









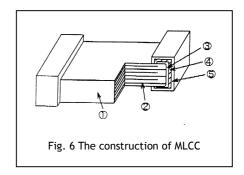
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APPENDIXES

Constructions

No.	Nam	ne	X7R, X5R, Y5V
1	Ceramic n	naterial	BaTiO₃ based
2	Inner ele	ctrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
(5)		Outer layer	Sn



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering.
- b. To store products on the shelf and avoid exposure to moisture.
- c. Don't expose products to excessive shock, vibration, direct sunlight and so on.

■ Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

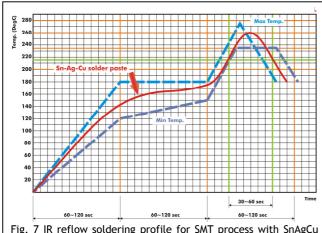


Fig. 7 IR reflow soldering profile for SMT process with \mbox{SnAgCu} series solder paste.

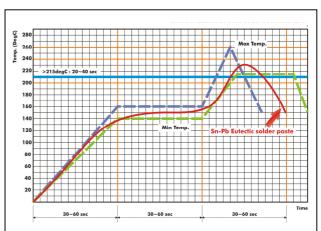


Fig. 8 IR reflow soldering profile for SMT process with eutectic SnPb solder paste.